# Description

# [METHOD FOR SYSTEM PERFORMANCE TESTING AND SELF CORRECTING ACTION]

### **BACKGROUND OF INVENTION**

[0001] Field of the Invention

[0002] The present invention relates to a method and structure to continuously evaluate microprocessor performance in the field and alter the parameters of the integrated circuit as performance degrades.

[0003] Description of the Related Art

[0004] Currently an additional amount of margin (additional guardband) is added to the performance criteria of every part when it is tested at the end of the manufacturing process. This assumes that each part is going to be negatively influenced by the degrade in performance, which is not realistic because the chip will only need the added margin if the critical path(s) are negatively effected, which

does not always occur. The invention described below addresses these issues.

### **SUMMARY OF INVENTION**

[0005] The invention provides a method and apparatus for autonomously self-monitoring and self-adjusting the operation of an integrated circuit device throughout the integrated circuit device's useful life. The invention periodically performs performance self-testing on the integrated circuit device throughout the integrated circuit device's useful life. The invention also evaluates whether results from the self-testing are within acceptable limits and self-adjusts parameters of the integrated circuit device until the results from the self-testing are within the acceptable limits.

[0006] The performance self-testing can be, for example, builtin self testing (BIST), functional testing, or similar testing.
For example, the invention can loop through functional
test sequences until failure, and then evaluate the results
by comparing the failure criteria, i.e. frequency, temperature, etc. against predetermined limits. In order to selfadjust the circuit, the invention can alter the voltage supplied to portions of the integrated circuit device by, for
example, activating electronic fuses to permanently

change the parameters of voltage regulators. Also, the invention can maintain a history of adjustments made to the circuit's parameters that can be read or uploaded later.

[0007] The invention thereby provides a self-monitoring and self-correcting integrated circuit device. Such a device includes a self-testing controller adapted to periodically perform performance self-testing on the integrated circuit device throughout the useful life of the integrated circuit device, a comparator adapted to evaluate whether results from the self-testing are within acceptable limits, and a parameter processor adapted to permanently self-adjust parameters of the integrated circuit device until the results from the self-testing are within the acceptable limits.

The inventive device can include built-in self test (BIST) units, functional testing units, etc. Such a functional testing unit can apply functional test sequences to the integrated circuit device until failure, and a comparator can be used to compare the failure frequency against predetermined limits. The processor adjusts the parameters by, for example, altering the voltage supplied to portions of the integrated circuit device. Thus, for example, the processor can activate electronic fuses to permanently change the

parameters of the voltage produced by voltage regulators. This structure can also include a permanent storage device adapted to maintain a history of adjustments made to the parameters by the processor.

[0009] By periodically checking performance characteristics of the integrated circuit device, the invention is able to recognize when the performance of the device begins to degrade or for wear out mechanisms (such as hot electron carriers) and make appropriate parameter changes to compensate for performance degradation.

[0010] These, and other, aspects and objects of the present invention will be better appreciated and understood when considered in conjunction with the following description and the accompanying drawings. It should be understood, however, that the following description, while indicating preferred embodiments of the present invention and numerous specific details thereof, is given by way of illustration and not of limitation. Many changes and modifications may be made within the scope of the present invention without departing from the spirit thereof, and the invention includes all such modifications.

**BRIEF DESCRIPTION OF DRAWINGS** 

[0011] The invention will be better understood from the following

detailed description with reference to the drawings, in which: Figure 1 is a schematic diagram of a system illustrating the invention;

- [0012] Figure 2 is a flow diagram illustrating a preferred method of the invention; and
- [0013] Figure 3 is a flow diagram illustrating a preferred method of the invention.

## **DETAILED DESCRIPTION**

[0014] The present invention and the various features and advantageous details thereof are explained more fully with reference to the non-limiting embodiments that are illustrated in the accompanying drawings and detailed in the following description. It should be noted that the features illustrated in the drawings are not necessarily drawn to scale. Descriptions of well-known components and processing techniques are omitted so as to not unnecessarily obscure the present invention. The examples used herein are intended merely to facilitate an understanding of ways in which the invention may be practiced and to further enable those of skill in the art to practice the invention. Accordingly, the examples should not be construed as limiting the scope of the invention.

[0015] As shown in Figure 1, the invention provides a self-

monitoring and self-correcting integrated circuit device 100. This structure 100 is designed to enable on-chip performance self-testing periodically and/or during each boot up. Such a device includes a self-testing controller 114 (e.g., microprocessor) adapted to periodically perform performance self-testing on the integrated circuit device throughout the useful life of the integrated circuit device. The controller 110 can also include built-in self test (BIST) units 120 (part of which can be located within the processor and part of which can be located within the components themselves), functional testing units 122, etc. For many microprocessors this could constitute using AC LBIST (via On Product Clock Generation) and ABIST. A comparator 124 (which can be part of, or separate from the controller 114) evaluates whether results from the self-testing are within acceptable limits. A parameter processor 126 permanently self-adjusts parameters of the integrated circuit device until the results from the selftesting are within the acceptable limits. Item 110 represents the product being tested.

[0016] In one example, the functional testing unit 122 can apply functional test sequences to the integrated circuit device until failure, and the comparator 124 can be used to com-

pare the failure frequency against predetermined limits. The parameter processor 126 adjusts the parameters by, for example, altering the voltage supplied to portions of the integrated circuit device. Thus, for example, the parameter processor 126 can activate electronic fuses (efuses) 128 in a bank to permanently change the parameters of the voltage produced by voltage regulators 116 (e.g., by affecting the voltage reference module 118). This structure can also include permanent storage 130 (e.g., ROM internal or external to the microprocessor 114) adapted to maintain a history of adjustments made to the parameters by the processor. This storage 130 can be accessed (e.g., read or uploaded) later to gather statistics regarding common failures of specific designs.

[0017] Figure 2 illustrates the processing details of one exemplary functional test flow where the invention enables performance margin self-testing in the field through microcoded functional patterns. In this example, the functional patterns that are performance critical can be identified and microcoded onto either the product 110 or system ROM 130. Either the microprocessor 114 or a system counter 112 keeps a count of time to identify specific intervals of when to launch a performance diagnostic rou-

tine 200. During this time, a spread spectrum phase lock loop (PLL) 132 can be ramped up to a lock frequency from an original set point 202. During this time when the PLL frequency is rising, the microprocessor loops on the microcoded functional test sequences until failure 204. Typically, the ramp time for the spread spectrum PLL is on the order of a hundred microseconds, which would provide sufficient time for testing, after which the PLL 132 would return to the original functional lock frequency.

[0018]

The failure frequency is then compared against a predetermined limit for acceptable margin 206. If the fail frequency exceeds the criteria then no action is taken 210. If the margin does not exceed the performance criteria then a bit is set within a voltage regulation bank of efuses 208. Thus, if the available margin is not acceptable 206, the microprocessor would communicate the need for an uplift of voltage 208 from the off chip regulator 116. This bank of fuses 128 is used during final test to determine the voltage range that the external regulator 116 needs to supply. Industry available regulators read values called the VID (voltage ID) from the microprocessor and set their output levels accordingly. Using efuse technology, if a part fails the test of performance margin requirements,

the next voltage level bit is blown into the efuses which, in turn, drives the voltage regulator 116 to a higher state. For example, some voltage regulators change in 25mV incremental steps.

[0019] Figure 3 illustrates a more general flow of the autonomously self-monitoring and self-adjusting operation of the integrated circuit device throughout the integrated circuit device's useful life inventive system. More specifically, in item 300, the invention periodically performs performance self-testing on the integrated circuit device throughout the integrated circuit devices useful life. The invention also evaluates whether results from the selftesting are within acceptable limits 302 and self-adjusts parameters of the integrated circuit device until the results from the self-testing are within the acceptable limits 304. One parameter that can be adjusted is the voltage supplied to the various components, as discussed above. However, the invention is not limited to merely adjusting the voltage, and the invention can also adjust a number of different parameters such as the delay (by engaging or disengaging various latches, again through the use of fuses), processing speed (by adjusting the various multipliers), thermal cooling required (by adjusting the inte-

grated circuits fan speed), repair initiation (by engaging, for example, spare array redundant structures), etc.. As discussed above, the performance self-testing 300 can be, for example, built-in self testing (BIST), functional testing, or similar testing. For example, the invention can loop through functional test sequences until failure, and then evaluate the results by comparing the failure frequency against predetermined limits. In order to selfadjust the circuit 304, the invention can alter the voltage supplied to portions of the integrated circuit device by, for example, activating electronic fuses to permanently change the parameters of voltage regulators. Also, the invention can maintain a history of adjustments made to the circuit's parameters 306 that can be read or uploaded later. Processing then loops back to the periodic selftesting 300.

[0020] One advantage of this methodology is the elimination the added performance requirement (additional guardband) at final manufacturing test, which can be 1–3%. In other words, before the invention is completed, a compensating performance increase (e.g., by increasing voltage, increasing acceptable delay times, thermal margin, frequency margin, etc.), that were not necessary in defect free de-

vices. However, as the device performance degrades over the device's useful life, such compensating performance increases (quardband) would allow the device to continue to operate effectively. Unfortunately, sometimes the compensating performance increase was not sufficient to overcome the performance degradation and sometimes the compensate performance increase was unnecessary; in that the device's performance never degraded to the point that was forecast. These (sometimes unnecessary or ineffective) compensating performance increases (guardband) decrease the overall performance of the device and increase its manufacturing cost. By eliminating the need for these forecasted compensating performance increases, the invention allows the device to be made less expensively and to provide increased performance (at least initially).

[0021] This inventive self-checking and self-adjusting process could continue over the lifetime of the product provided the fuses could be set appropriately and that the voltage would not challenge the maximum voltage of parts. By periodically checking performance characteristics of the integrated circuit device, the invention is able to recognize when the performance of the device begins to degrade

(such as increases in hot electron carriers) and make appropriate parameter changes to compensate for performance degradation.

[0022] Additional applications where this invention could be applied are the thermal compensation required for an individual integrated circuit. For example, in the design of a complex computer system many variables are set at fixed points to allow for a solution. Often these fixed points are at the worst possible level and components are statically fixed for operation in these conditions. However each system will be in a different environment and the margin built into the system may cost the user in a variety of ways. Thermal control is often achieved through the use of fans which can be very loud. By autonomously testing the system in a field, self correction could be achieved and the overall noise generated by the fan could be optimized.

[0023] In another application it must be considered that not only does wear out effect performance but it can affect overall functionality. An example that uses common circuitry already available on many designs would be to test the functionality of the memory of an integrated circuit. During manufacturing testing defective section of memory

can be replaced through the use of spare (or redundant) memory elements. Similarly, the faulty function of memory in the field could be replaced by redundant memory through autonomous testing and the use of efuse technology to enable and disable the memory components.

[0024] While the invention has been described in terms of preferred embodiments, those skilled in the art will recognize that the invention can be practiced with modification within the spirit and scope of the appended claims.